

ENGIS[®] MICROTECH (MPC) MACHINE FOR MAXIMUM PROCESS CONTROL



The **Engis Corporation** has introduced the MPC precision surface preparation system for the finishing of Advanced Materials.

This system is specifically designed for unique polishing, delayering and planarization applications where R&D, prototype and small volume processing is required. It is ideal for polishing Advanced Materials such as silicon carbide, sapphire, metal foils or the delayering planarization of SiO₂ and metalized depositions.

The MPC system has been designed with the kinematics and control to allow development of processes that have 6-Sigma capability for material removal, flatness and surface finish generation. The menu-driven microprocessor control allows any polishing, delayering or planarization process to be fully optimized. The oscillation system provides 3-axis motion for true CMP kinematics.

ADVANCED MATERIALS PRODUCTS

FOR ADDITIONAL INFORMATION CONTACT THE ENGIS MICROTECH TEAM AT

WWW.ENGISCA.COM



MPC SPECIFICATIONS

- This system is ideal for universities and research establishments as well as commercial companies with unique, applications-specific requirements
- The Engis Microtech technical team has developed a range of standard processes that can be applied to this machine
- Conventional abrasives, plates and other consumables/accessories can be employed as well as Engis precision diamond CPM-D slurries
- Competitively priced
- The system can be purchased with basic operator training or with a process development or application specific technology package
- Touch-screen operator interface which can be enhanced
- Operator interface mounted on a swivel-style pendant
- All drives are programmable and reversible
- Data acquisition system and program stringing
- Oscillation features are controlled from the main input screen
- Slurry dispensing system controls integrated
- Digital readouts for all drive and pressure functions

TECHNICAL DATA	
LAPPING PLATE DIAMETER	400MM (16") 450MM (18") 500MM (20")
NO. OF STATIONS	2
POWER HEADS	2
WORK TABLE DIMENSIONS	41" W x 37" D
PLATE RPM RANGE	3-130 RPM
POWER HEAD SPINDLE SPEED	2 - 100 RPM (REVERSABLE)
ARM SPINDLE RANGE	5-100 RPM
MAIN SPINDLE RANGE	5-130 RPM
ARM FORCE MAXIMUM	100 PSI
POWER HEAD DOWN PRESSURE	2.25 - 45 KGMS (5 - 100 LBS)
POWER STATION PRESSURE AND SPEED RAMP-UP	ADJUSTABLE & PROGRAMMABLE
MAIN DRIVE MOTOR (H.P. RATING)	1.5 H.P. AIR COOLED
OPERATING VOLTAGE	230 VAC, 3-PHASE, 50/60 HZ
COMPUTER CONTROLLED INTERFACE	STANDARD
DIMENSIONS	64" W x 43" D x 78" H
ESTIMATED SHIPPING WEIGHT	1,200 LBS

*ENGIS IS ABLE TO DELIVER A COMPLETE SYSTEM TO FIT EACH CUSTOMER'S UNIQUE REQUIREMENTS
AND OPTIMIZE THE MOST DEMANDING APPLICATIONS*

- HYPREZ COMPOSITE LAP PLATES
- POLISHING PADS/CLOTHS
- DIAMOND AND COLLOIDAL LAPPING & POLISHING SLURRIES
- WAFER MOUNTING EQUIPMENT



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